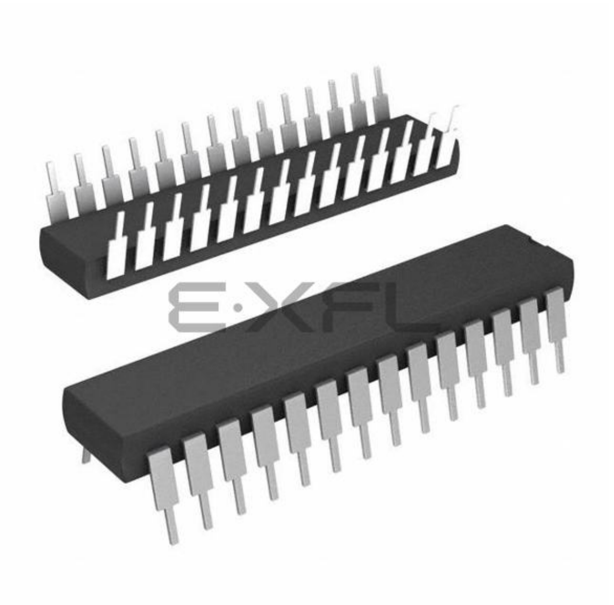


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc66-04i-sp

TABLE 4-6: SPECIAL FUNCTION REGISTERS FOR THE PIC16C66/67 (Cont.'d)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets[(3)]
Bank 2											
100h[(1)]	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
101h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
102h[(1)]	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
103h[(1)]	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
104h[(1)]	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
105h	—	Unimplemented								—	—
106h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
107h	—	Unimplemented								—	—
108h	—	Unimplemented								—	—
109h	—	Unimplemented								—	—
10Ah[(1,2)]	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
10Bh[(1)]	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
10Ch-10Fh	—	Unimplemented								—	—
Bank 3											
180h[(1)]	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
181h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
182h[(1)]	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
183h[(1)]	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
184h[(1)]	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
185h	—	Unimplemented								—	—
186h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
187h	—	Unimplemented								—	—
188h	—	Unimplemented								—	—
189h	—	Unimplemented								—	—
18Ah[(1,2)]	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
18Bh[(1)]	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
18Ch-19Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.

2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)

3: Other (non power-up) resets include external reset through $\overline{MCLR}$ and the Watchdog Timer reset.

4: PIE1<6> and PIR1<6> are reserved on the PIC16C66/67, always maintain these bits clear.

5: PORTD, PORTE, TRISD, and TRISE are not implemented on the PIC16C66, read as '0'.

6: PSPIF (PIR1<7>) and PSPIE (PIE1<7>) are reserved on the PIC16C66, maintain these bits clear.

Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that the PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

```
ORG 0x500
BSF     PCLATH,3   ;Select page 1 (800h-FFFh)
BCF     PCLATH,4   ;Only on >4K devices
CALL    SUB1_P1    ;Call subroutine in
        :          ;page 1 (800h-FFFh)
        :
        :
ORG 0x900
SUB1_P1:           ;called subroutine
        :          ;page 1 (800h-FFFh)
        :
RETURN             ;return to Call subroutine
                   ;in page 0 (000h-7FFh)
```

4.5 Indirect Addressing, INDF and FSR Registers

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

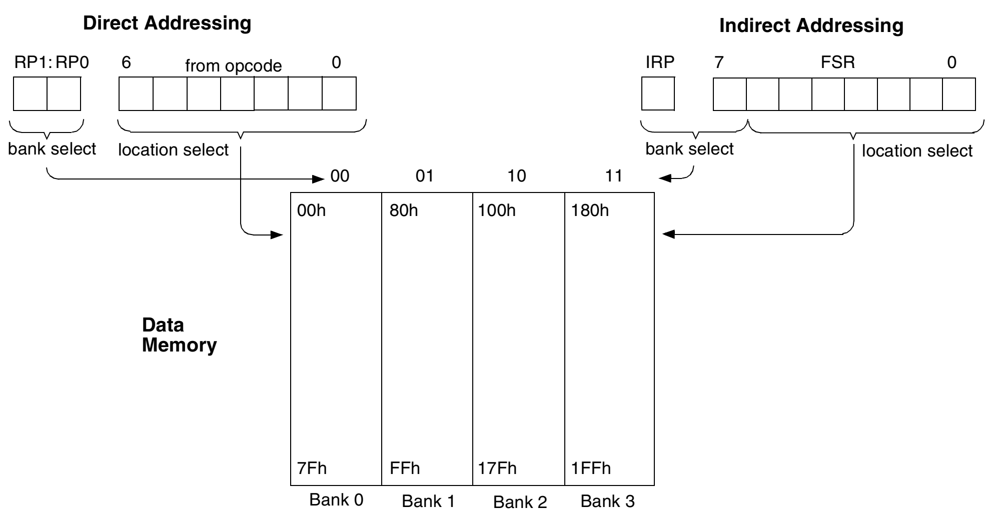
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = '0') will produce 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-25.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 4-2.

EXAMPLE 4-2: INDIRECT ADDRESSING

```
          movlw   0x20    ;initialize pointer
          movwf   FSR     ;  to RAM
NEXT      clrf    INDF    ;clear INDF register
          incf    FSR,F   ;inc pointer
          btfss   FSR,4   ;all done?
          goto    NEXT    ;NO, clear next
CONTINUE
          :               ;YES, continue
```

FIGURE 4-25: DIRECT/INDIRECT ADDRESSING



For memory map detail see Figure 4-5, Figure 4-6, Figure 4-7, and Figure 4-8.

5.0 I/O PORTS

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

Some pins for these I/O ports are multiplexed with an alternate function(s) for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Register

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

All devices have a 6-bit wide PORTA, except for the PIC16C61 which has a 5-bit wide PORTA.

Pin RA4/T0CKI is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as output or input.

Setting a bit in the TRISA register puts the corresponding output driver in a hi-impedance mode. Clearing a bit in the TRISA register puts the contents of the output latch on the selected pin.

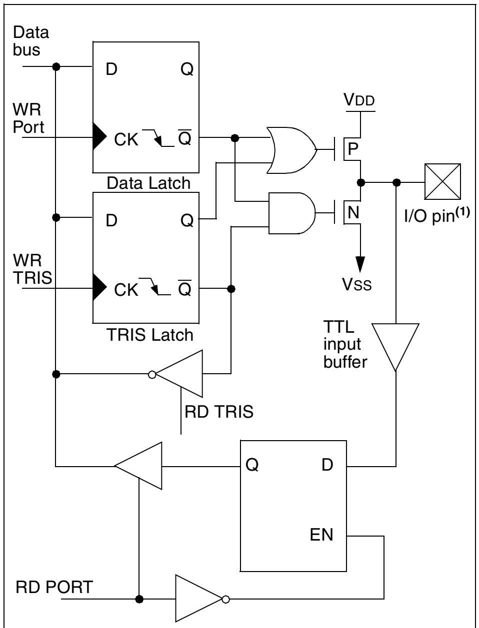
Reading PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified, and then written to the port data latch.

Pin RA4 is multiplexed with Timer0 module clock input to become the RA4/T0CKI pin.

EXAMPLE 5-1: INITIALIZING PORTA

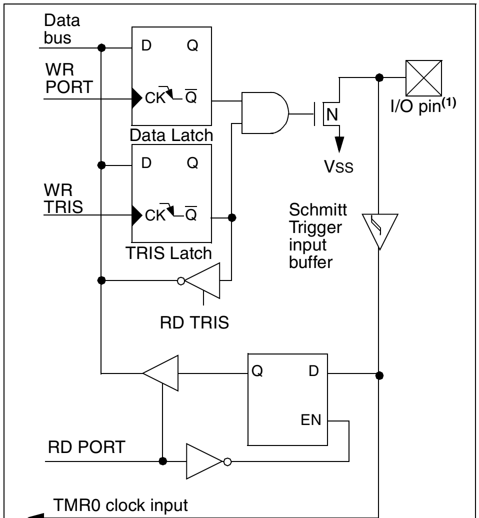
```
BCF     STATUS, RP0   ;
BCF     STATUS, RP1   ; PIC16C66/67 only
CLRF    PORTA         ; Initialize PORTA by
                      ; clearing output
                      ; data latches
BSF     STATUS, RP0   ; Select Bank 1
MOVLW   0xCF          ; Value used to
                      ; initialize data
                      ; direction
MOVWF   TRISA         ; Set RA<3:0> as inputs
                      ; RA<5:4> as outputs
                      ; TRISA<7:6> are always
                      ; read as '0'.
```

FIGURE 5-1: BLOCK DIAGRAM OF THE RA3:RA0 PINS AND THE RA5 PIN



Note 1: I/O pins have protection diodes to VDD and VSS.
2: The PIC16C61 does not have an RA5 pin.

FIGURE 5-2: BLOCK DIAGRAM OF THE RA4/T0CKI PIN



Note 1: I/O pin has protection diodes to VSS only.

10.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 10-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 10-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF   CCP1CON     ; Turn CCP module off
MOVLW  NEW_CAPT_PS ; Load the W reg with
                   ; the new prescaler
                   ; mode value and CCP ON
MOVWF  CCP1CON     ; Load CCP1CON with
; this value
```

10.2 Compare Mode

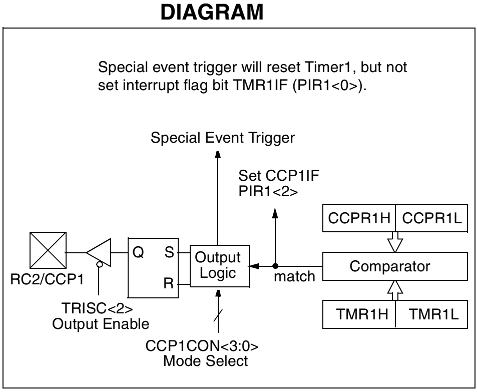
Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RC2/CCP1 pin is:

- Driven High
- Driven Low
- Remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time interrupt flag bit CCP1IF is set.

FIGURE 10-3: COMPARE MODE OPERATION BLOCK DIAGRAM



10.2.1 CCP PIN CONFIGURATION

The user must configure the RC2/CCP1 pin as an output by clearing the TRISC<2> bit.

> **Note:** Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the data latch.

10.2.1 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

10.2.2 SOFTWARE INTERRUPT MODE

When Generate Software Interrupt is chosen, the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

10.2.3 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated which may be used to initiate an action.

The special event trigger output of CCP1 and CCP2 resets the TMR1 register pair. This allows the CCPR1H:CCPR1L and CCPR2H:CCPR2L registers to effectively be 16-bit programmable period register(s) for Timer1.

For compatibility issues, the special event trigger output of CCP1 (PIC16C72) and CCP2 (all other PIC16C7X devices) also starts an A/D conversion.

> **Note:** The “special event trigger” from the CCP1and CCP2 modules will not set interrupt flag bit TMR1IF (PIR1<0>).

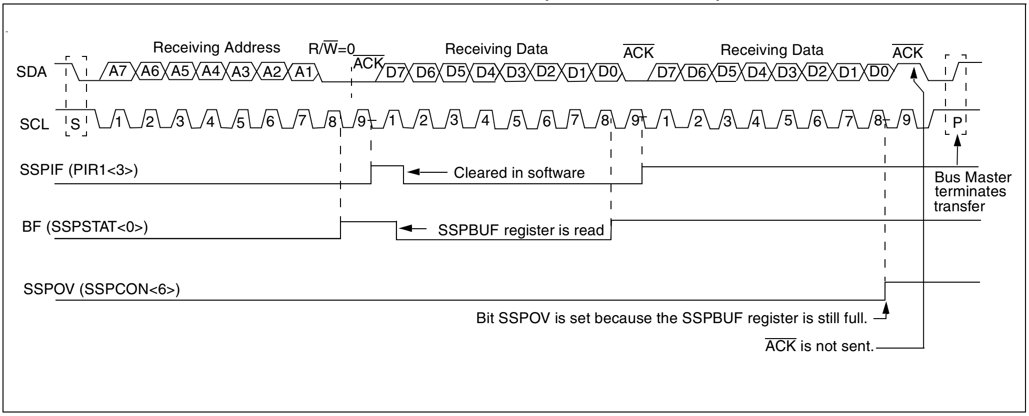
11.5.1.2 RECEPTION

When the $R/\overline{W}$ bit of the address byte is clear and an address match occurs, the $R/\overline{W}$ bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register.

When the address byte overflow condition exists, then no acknowledge ($\overline{ACK}$) pulse is given. An overflow condition is defined as either bit BF (SSPSTAT<0>) is set or bit SSPOV (SSPCON<6>) is set.

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF (PIR1<3>) must be cleared in software. The SSPSTAT register is used to determine the status of the byte.

FIGURE 11-25: I^2C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)



12.4 USART Synchronous Slave Mode

Applicable Devices													
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

Synchronous Slave Mode differs from Master Mode in the fact that the shift clock is supplied externally at the CK pin (instead of being supplied internally in master mode). This allows the device to transfer or receive data while in SLEEP mode. Slave mode is entered by clearing bit CSRC (TXSTA<7>).

12.4.1 USART SYNCHRONOUS SLAVE TRANSMIT

The operation of the synchronous master and slave modes are identical except in the case of the SLEEP mode.

If two words are written to the TXREG and then the `SLEEP` instruction is executed, the following will occur:

a) The first word will immediately transfer to the TSR register and transmit.
b) The second word will remain in TXREG register.
c) Flag bit TXIF will not be set.
d) When the first word has been shifted out of TSR, the TXREG register will transfer the second word to the TSR and flag bit TXIF will now be set.
e) If enable bit TXIE is set, the interrupt will wake the chip from SLEEP and if the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

Steps to follow when setting up Synchronous Slave Transmission:

1. Enable the synchronous slave serial port by setting bits SYNC and SPEN, and clearing bit CSRC.
2. Clear bits CREN and SREN.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.

12.4.2 USART SYNCHRONOUS SLAVE RECEPTION

The operation of the synchronous master and slave modes is identical except in the case of the SLEEP mode. Also, enable bit SREN is a don't care in slave mode.

If receive is enabled by setting bit CREN prior to the `SLEEP` instruction, then a word may be received during SLEEP. On completely receiving the word, the RSR register will transfer the data to the RCREG register and if enable bit RCIE is set, the interrupt generated will wake the chip from SLEEP. If the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

Steps to follow when setting up a Synchronous Slave Reception:

1. Enable the synchronous master serial port by setting bits SYNC and SPEN, and clearing bit CSRC.
2. If interrupts are desired, then set enable bit RCIE.
3. If 9-bit reception is desired, then set bit RX9.
4. To enable reception, set enable bit CREN.
5. Flag bit RCIF will be set when reception is complete, and an interrupt will be generated if enable bit RCIE was set.
6. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
7. Read the 8-bit received data by reading the RCREG register.
8. If any error occurred, clear the error by clearing enable bit CREN.

FIGURE 13-2: CONFIGURATION WORD FOR PIC16C62/64/65

—	—	—	—	—	—	—	—	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0

bit13 bit0

Register: CONFIG
Address 2007h

bit 13-6: **Unimplemented**: Read as '1'

bit 5-4: **CP1:CP0**: Code Protection bits
11 = Code protection off
10 = Upper half of program memory code protected
01 = Upper 3/4th of program memory code protected
00 = All memory is code protected

bit 3: **PWRTE**: Power-up Timer Enable bit
1 = Power-up Timer enabled
0 = Power-up Timer disabled

bit 2: **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

FIGURE 13-3: CONFIGURATION WORD FOR PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67

CP1	CP0	CP1	CP0	CP1	CP0	—	BODEN	CP1	CP0	$\overline{\text{PWRTE}}$	WDTE	FOSC1	FOSC0

bit13 bit0

Register: CONFIG
Address 2007h

bit 13-8: **CP1:CP0**: Code Protection bits(2)
bit 5:4
11 = Code protection off
10 = Upper half of program memory code protected
01 = Upper 3/4th of program memory code protected
00 = All memory is code protected

bit 7: **Unimplemented**: Read as '1'

bit 6: **BODEN**: Brown-out Reset Enable bit (1)
1 = Brown-out Reset enabled
0 = Brown-out Reset disabled

bit 3: **$\overline{\text{PWRTE}}$**: Power-up Timer Enable bit (1)
1 = Power-up Timer disabled
0 = Power-up Timer enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{\text{PWRTE}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.
2: All of the CP1:CP0 pairs have to be given the same value to implement the code protection scheme listed.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

Data based on matrix samples. See first page of this section for details.

FIGURE 16-17: TRANSCONDUCTANCE (gm) OF LP OSCILLATOR vs. VDD

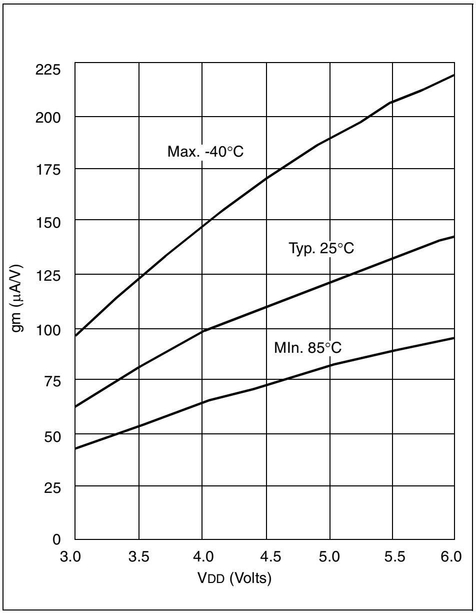


FIGURE 16-18: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD

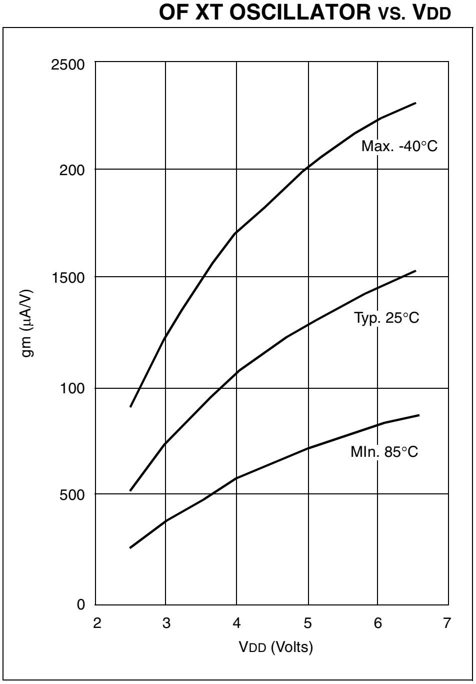


FIGURE 16-19: IOH vs. VOH, VDD = 3V

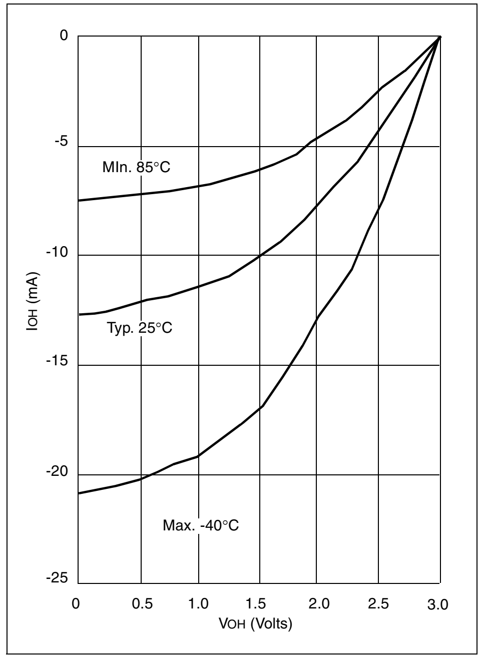
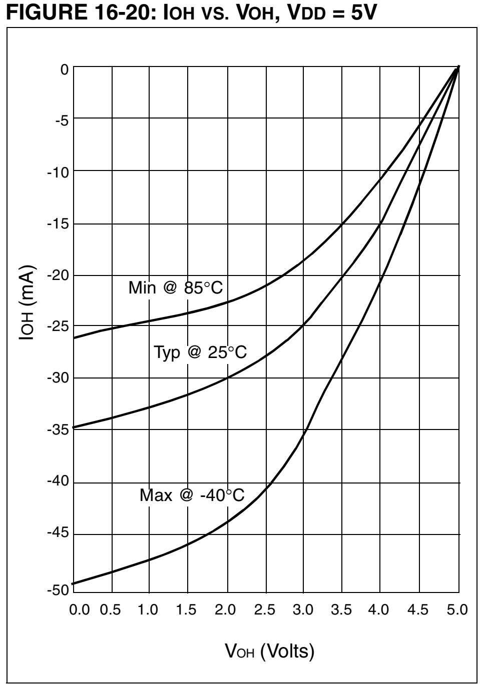


FIGURE 16-20: IOH vs. VOH, VDD = 5V



Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

17.1 DC Characteristics: PIC16C62/64-04 (Commercial, Industrial) PIC16C62/64-10 (Commercial, Industrial) PIC16C62/64-20 (Commercial, Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001 D001A	Supply Voltage	VDD	4.0 4.5	- -	6.0 5.5	V V	XT, RC and LP osc configuration HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2, 5)	IDD	-	2.7	5.0	mA	XT, RC, osc configuration FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	13.5	30	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D020 D021 D021A	Power-down Current (Note 3, 5)	IPD	- - -	10.5 1.5 1.5	42 21 24	μA μA μA	VDD = 4.0V, WDT enabled, -40°C to +85°C VDD = 4.0V, WDT disabled, -0°C to +70°C VDD = 4.0V, WDT disabled, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

17.3 DC Characteristics: PIC16C62/64-04 (Commercial, Industrial)
PIC16C62/64-10 (Commercial, Industrial)
PIC16C62/64-20 (Commercial, Industrial)
PIC16LC62/64-04 (Commercial, Industrial)

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC spec Section 17.1 and Section 17.2						
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{MCLR}$, OSC1 (in RC mode)		Vss	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH					
D040	with TTL buffer		2.0	-	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD		For entire VDD range
D042	$\overline{MCLR}$		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	200	400	μA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	μA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	μA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	**Open-Drain High Voltage**	VOD	-	-	14	V	RA4 pin

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

18.5 Timing Diagrams and Specifications

FIGURE 18-2: EXTERNAL CLOCK TIMING

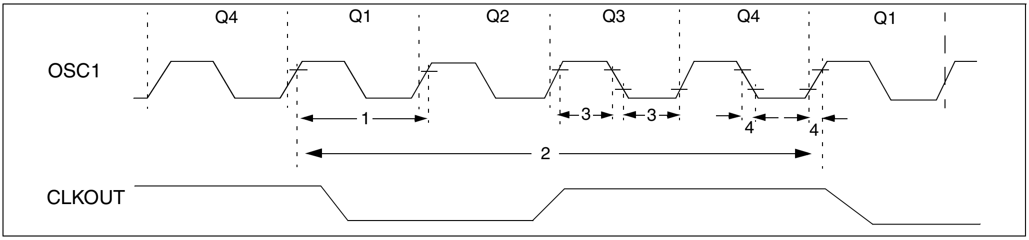


TABLE 18-2: EXTERNAL CLOCK TIMING REQUIREMENTS

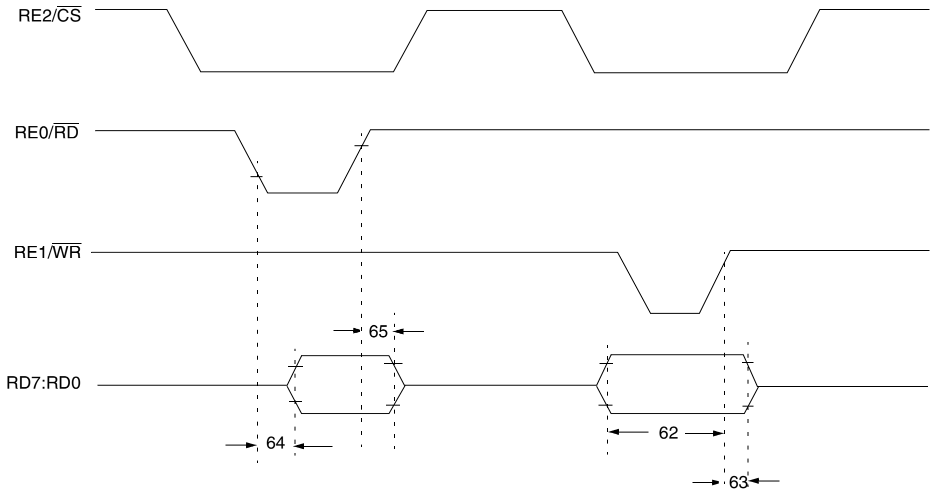
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period (Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	**External Clock in (OSC1) High or Low Time**	100	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 19-7: PARALLEL SLAVE PORT TIMING



Note: Refer to Figure 19-1 for load conditions

TABLE 19-7: PARALLEL SLAVE PORT REQUIREMENTS

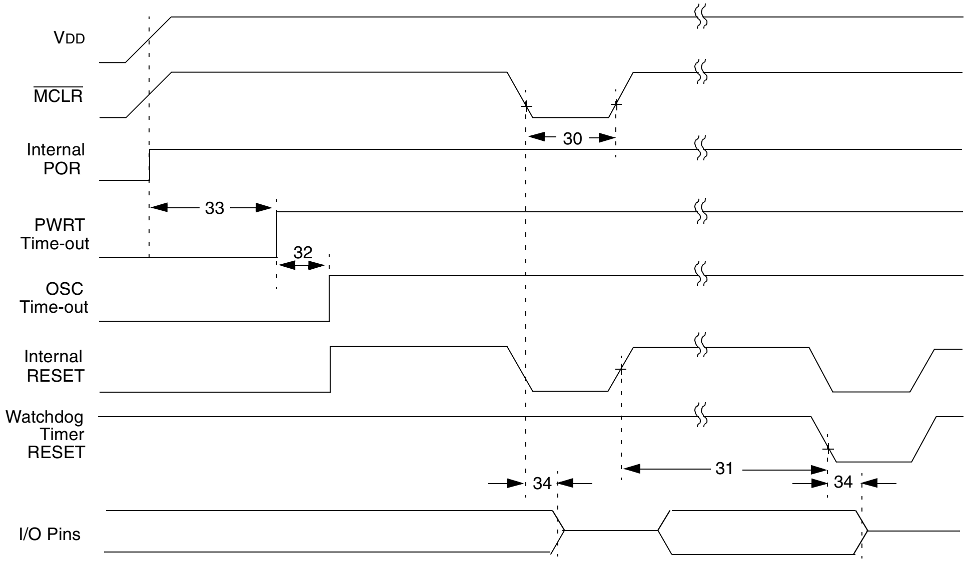
Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before WR↑ or CS↑ (setup time)		20	—	—	ns	
63*	TwrH2dtI	WR↑ or CS↑ to data–in invalid (hold time)	PIC16**C**65	20	—	—	ns	
			PIC16**LC**65	35	—	—	ns	
64	TrdL2dtV	RD↓ and CS↓ to data–out valid		—	—	80	ns	
65	TrdH2dtI	RD↑ or CS↑ to data–out invalid		10	—	30	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 21-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 21-1 for load conditions.

FIGURE 21-5: BROWN-OUT RESET TIMING

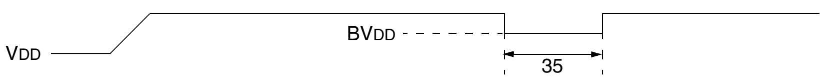


TABLE 21-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

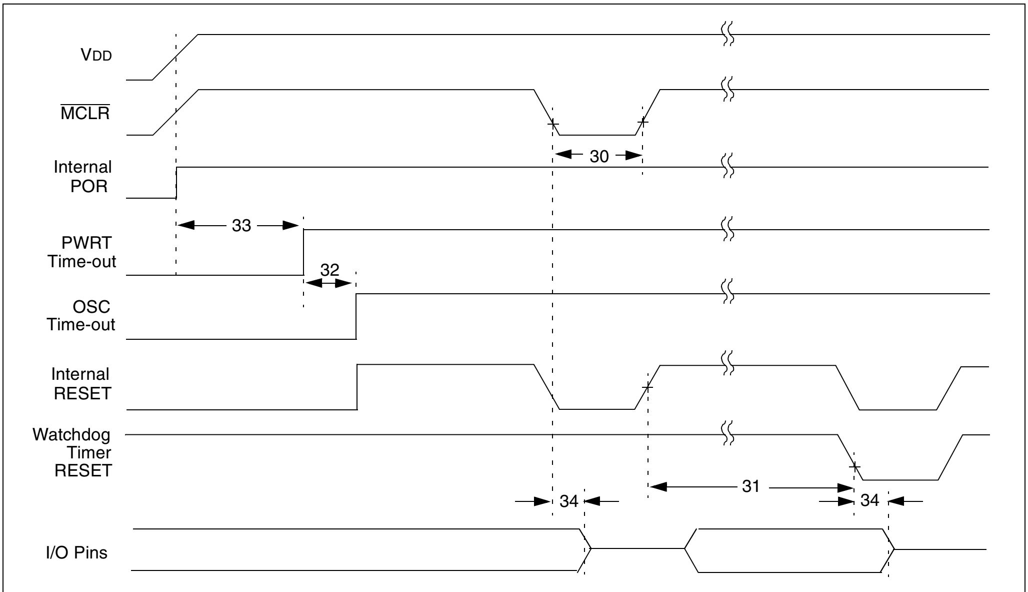
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or WDT reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset Pulse Width	100	—	—	μs	VDD ≤ BVDD (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 22-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-5: BROWN-OUT RESET TIMING

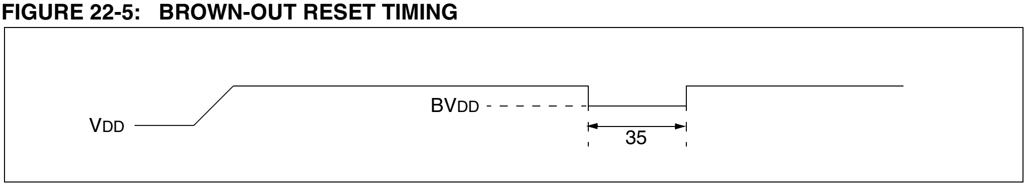


TABLE 22-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	TIOZ	I/O Hi-impedance from $\overline{\text{MCLR}}$ Low or WDT reset	—	—	2.1	µs	
35	TBOR	Brown-out Reset Pulse Width	100	—	—	µs	VDD ≤ BVDD (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

FIGURE 23-18: TYPICAL IDD vs. CAPACITANCE @ 500 kHz (RC MODE)

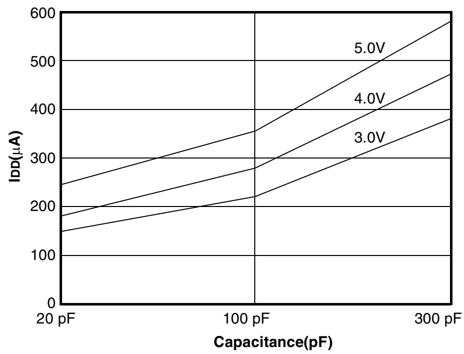
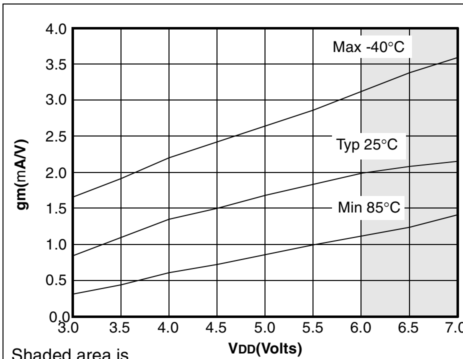


TABLE 23-1: RC OSCILLATOR FREQUENCIES

Cext	Rext	Average Fosc @ 5V, 25°C	
22 pF	5k	4.12 MHz	± 1.4%
	10k	2.35 MHz	± 1.4%
	100k	268 kHz	± 1.1%
100 pF	3.3k	1.80 MHz	± 1.0%
	5k	1.27 MHz	± 1.0%
	10k	688 kHz	± 1.2%
	100k	77.2 kHz	± 1.0%
300 pF	3.3k	707 kHz	± 1.4%
	5k	501 kHz	± 1.2%
	10k	269 kHz	± 1.6%
	100k	28.3 kHz	± 1.1%

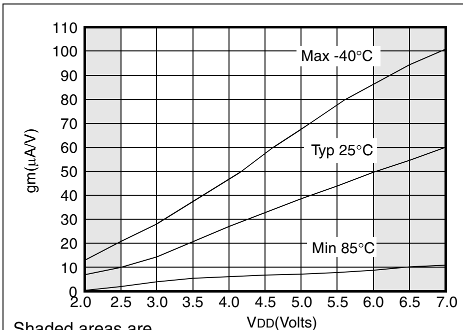
The percentage variation indicated here is part to part variation due to normal process distribution. The variation indicated is ±3 standard deviation from average value for VDD = 5V.

FIGURE 23-19: TRANSCONDUCTANCE(gm) OF HS OSCILLATOR vs. VDD



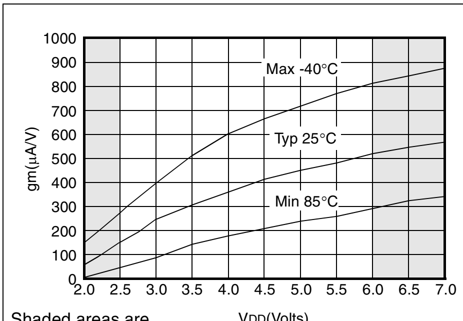
Shaded area is beyond recommended range

FIGURE 23-20: TRANSCONDUCTANCE(gm) OF LP OSCILLATOR vs. VDD



Shaded areas are beyond recommended range

FIGURE 23-21: TRANSCONDUCTANCE(gm) OF XT OSCILLATOR vs. VDD

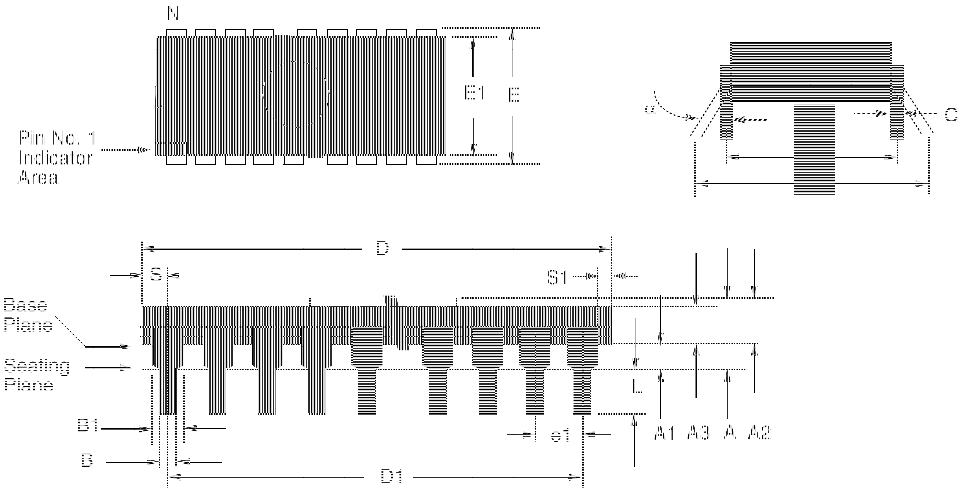


Shaded areas are beyond recommended range

Data based on matrix samples. See first page of this section for details.

24.8 40-Lead Ceramic CERDIP Dual In-line with Window (600 mil) (JW)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Ceramic CERDIP Dual In-Line (CDP)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	4.318	5.715		0.170	0.225	
A1	0.381	1.778		0.015	0.070	
A2	3.810	4.699		0.150	0.185	
A3	3.810	4.445		0.150	0.175	
B	0.355	0.585		0.014	0.023	
B1	1.270	1.651	**Typical**	0.050	0.065	**Typical**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	51.435	52.705		2.025	2.075	
D1	48.260	48.260	**Reference**	1.900	1.900	**Reference**
E	15.240	15.875		0.600	0.625	
E1	12.954	15.240		0.510	0.600	
e1	2.540	2.540	**Reference**	0.100	0.100	**Reference**
eA	14.986	16.002	**Typical**	0.590	0.630	**Typical**
eB	15.240	18.034		0.600	0.710	
L	3.175	3.810		0.125	0.150	
N	40	40		40	40	
S	1.016	2.286		0.040	0.090	
S1	0.381	1.778		0.015	0.070	

APPENDIX A: MODIFICATIONS

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. PA2, PA1, PA0 bits are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: `RETURN`, `RETFIE`, `ADDLW`, and `SUBLW`. Two instructions `TRIS` and `OPTION` are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from SLEEP through interrupt is added.
11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT), are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. Timer0 pin is also a port pin (RA4/T0CKI) now.
14. FSR is made a full 8-bit register.
15. “In-circuit programming” is made possible. The user can program PIC16CXX devices using only five pins: V_{DD}, V_{SS}, V_{PP}, RB6 (clock) and RB7 (data in/out).
16. Power Control register (PCON) is added with a Power-on Reset status bit ($\overline{POR}$).(Not on the PIC16C61).
17. Brown-out Reset has been added to the following devices: PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for `CALL`, `GOTO`.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change reset vector to 0000h.

APPENDIX C: WHAT'S NEW

Added PIC16CR63 and PIC16CR65 devices.

Added PIC16C66 and PIC16C67 devices. The PIC16C66/67 devices have 368 bytes of data memory distributed in 4 banks and 8K of program memory in 4 pages. These two devices have an enhanced SPI that supports both clock phase and polarity. The USART has been enhanced.

When upgrading to the PIC16C66/67 please note that the upper 16 bytes of data memory in banks 1,2, and 3 are mapped into bank 0. This may require relocation of data memory usage in the user application code.

Q-cycles for instruction execution were added to Section 14.0 Instruction Set Summary.

APPENDIX D: WHAT'S CHANGED

Minor changes, spelling and grammatical changes.

Divided SPI section into SPI for the PIC16C66/67 (Section 11.3) and SPI for all other devices (Section 11.2).

Added the following note for the USART. This applies to all devices except the PIC16C66 and PIC16C67.

For the PIC16C63/R63/65/65A/R65 the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information or use the PIC16C66/67.

APPENDIX E: REVISION E

January 2013 - Added a note to each package drawing.

NOTES:

